

INFORMATION DISCLOSURE CITATION PTO-1449	Atty. Docket No. 980404A	Serial No. Not Yet Assigned
	Applicant(s): Kazuhisa TSUNOI et al.	
	Filing Date: March 14, 2001	Group Art Unit: Not Yet Assigned

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U.S. PATENT DOCUMENTS

Examiner Initial	Document No.	Name	Date	Class	Subclass	Filing Date (If appropriate)
<u>JN</u>	AA	4,442,966	Jourdain et al.	4/17/84		
<u>JN</u>	AB	5,706,579	Ross	1/1998		
<u>JN</u>	AC	5,245,750	Crumly et al.	9/1993		
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<u>JN</u>	AH	07-193101	7/28/95	Japan	Yes (Abstract)
<u>JN</u>	AI	EP 0 753 890 A2	1/15/97	European	Yes
<u>JN</u>	AJ	EP 0 724 289 A2	7/31/96	European	Yes
<u>JN</u>	AK	EP 0 596 393 A1	5/11/94	European	Yes
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<u>JN</u>	AN	JP 6-302649	10/28/94	Japan	
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<u>JN</u>	AS	Yoshihiro Bessho et al. "A Stud-Bump-Bonding Technique For High Density Multi-Chip-Module" Proceedings of the Japan International Electric Manufacturing Technology Symposium, US, New York, IEEE, vol. SYMP. 14, 1993, pps 326-365
<u>JN</u>	AT	Copy of European Patent Office Communication for European Patent Application No. 98302110 including European Search Report dated February 21, 2000.
<u>JN</u>	AU	"Nomenclature For the Adhesive Industry" 1-1959, pp. 1-2 (156/325)
Examiner <u>JOSEPH NGUYEN</u> Date Considered <u>10/20/01</u>		

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